

# Inyoung Kim

## List of Publications by Year in descending order

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Version: 2024-02-01

23  
papers

648  
citations

759233

12  
h-index

677142

22  
g-index

23  
all docs

23  
docs citations

23  
times ranked

920  
citing authors

#	ARTICLE	IF	CITATIONS
1	Al-assisted reliability assessment for gravure offset printing system. Scientific Reports, 2022, 12, 2954.	3.3	3
2	Tension modeling and precise tension control of roll-to-roll system for flexible electronics. Flexible and Printed Electronics, 2021, 6, 015005.	2.7	16
3	Hybrid fabrication of LED matrix display on multilayer flexible printed circuit board. Flexible and Printed Electronics, 2021, 6, 024001.	2.7	13
4	Registration error analysis and compensation of roll-to-roll screen printing system for flexible electronics. Flexible and Printed Electronics, 2021, 6, 024003.	2.7	15
5	Improvement of electrical and mechanical properties of In-48Sn solder bumps for flexible LED signage using Cu-Ag nanoparticles. Flexible and Printed Electronics, 2021, 6, 034006.	2.7	2
6	IoT device fabrication using roll-to-roll printing process. Scientific Reports, 2021, 11, 19982.	3.3	16
7	Experimental Qualification of the Process of Electrostatic Spray Deposition. Coatings, 2019, 9, 294.	2.6	9
8	Mechanical and electrical properties of reverse-offset printed Sn-Ag-Cu solder bumps. Journal of Materials Processing Technology, 2018, 259, 126-133.	6.3	6
9	Fabrication of replica cliché with fine pattern using reverse offset printing process. Thin Solid Films, 2018, 647, 57-63.	1.8	2
10	Effect of particle size distribution on the mechanical and electrical properties of reverse-offset printed Sn-Ag-Cu solder bumps. Journal of Materials Science: Materials in Electronics, 2018, 29, 19620-19631.	2.2	3
11	Flash light sintering of ag mesh films for printed transparent conducting electrode. Thin Solid Films, 2017, 629, 60-68.	1.8	25
12	Employment of roll-offset printing for fabrication of solder bump arrays: Harnessing the rheological properties of lead-free solder pastes using particle size distribution. Microelectronic Engineering, 2016, 164, 128-134.	2.4	13
13	Cliché fabrication method using precise roll printing process with 5 um pattern width. Proceedings of SPIE, 2016, , .	0.8	0
14	Roll-offset printed transparent conducting electrode for organic solar cells. Thin Solid Films, 2015, 580, 21-28.	1.8	29
15	Quantitative measurement of ink-blanket adhesion for contact transfer printing inks. International Journal of Precision Engineering and Manufacturing, 2015, 16, 151-156.	2.2	9
16	Investigation on synchronization of the offset printing process for fine patterning and precision overlay. Journal of Applied Physics, 2014, 115, 234908.	2.5	25
17	Hybrid electrohydrodynamic atomization of nanostructured silver top contact for inverted organic solar cells. Solar Energy Materials and Solar Cells, 2014, 130, 156-162.	6.2	11
18	Transparent conductive film with printable embedded patterns for organic solar cells. Solar Energy Materials and Solar Cells, 2013, 109, 142-147.	6.2	84

#	ARTICLE	IF	CITATIONS
19	Roll offset printing process based on interface separation for fine and smooth patterning. Thin Solid Films, 2013, 548, 566-571.	1.8	33
20	Silver front electrode grids for ITO-free all printed polymer solar cells with embedded and raised topographies, prepared by thermal imprint, flexographic and inkjet roll-to-roll processes. Nanoscale, 2012, 4, 6032.	5.6	222
21	Effect of ink cohesive force on gravure offset printing. Microelectronic Engineering, 2012, 98, 587-589.	2.4	25
22	The effect of reduction atmospheres on the sintering behaviors of inkjet-printed Cu interconnectors. Journal of Applied Physics, 2010, 108, .	2.5	45
23	Reliability of gravure offset printing under various printing conditions. Journal of Applied Physics, 2010, 108, 102802.	2.5	42